

HEAT DISSIPATING MODULE OF AN INTEGRATED CIRCUIT OF A PORTABLE COMPUTER

ABSTRACT OF THE DISCLOSURE

A heat-dissipating module of an integrated circuit of a portable computer is provided. It includes a thermal pad, a heatsink, a heatpipe and a phase-transition material. The heatsink has a main portion and an extension portion. A small narrow cross-section area for transferring heat of the heatsink between the main portion and the extension portion is disposed. The heatsink has a round contact surface for solving the problem of poor heat transfer by four strip areas.